VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE TITLE:

The title was amended as follows:

--[Optoelectronic component group] LED COMPONENT GROUP WITH HEAT DISSIPATING SUPPORT--.

IN THE SPECIFICATION:

Page 1, the first paragraph was amended as follows:

--The invention relates to an optoelectronic component group [in accordance with the preamble of Claim 1]. This concerns, in particular, LED arrays which are arranged in a planar manner, for example surface lighting luminaires.--

Page 1, the fourth paragraph was amended as follows:

--The object of the present invention is to provide an optoelectronic component group [in accordance with the preamble of Claim 1] which realizes good heat dissipation in a simple, cost-saving and space-saving manner.—

Page 1, the last paragraph (lines 36-38), was canceled.

Page 5, between lines 27 and 30, "Figures" was amended to the following heading:

--BRIEF DESCRIPTION OF THE DRAWINGS--.

Page 6, line 1, "Description of the drawings" was amended to the following heading:

--DESCRIPTION OF THE PREFERRED EMBODIMENTS--.

IN THE CLAIMS:

Claims 1-13 were amended as follows:

--1. (amended) [Optoelectronic] An optoelectronic component group which is mounted on a support (3) and which comprises at least two adjacent LEDs (2) at a prescribed distance (a), and also associated connecting lines (4), [characterized in that] wherein the support (3) [is composed of a material having] has a thermal conductivity of [better than 1 W/Kxm, in particular of] at least 1.5 W/Kxm.—

--2. (amended) [Optoelectronic] The optoelectronic component group according to Claim [1] 14, [characterized in that] wherein the support is composed of a material which can be populated on said exterior mounting surface by means of SMD technology.—

--3. (amended) [Optoelectronic] The optoelectronic component group according to Claim 1, [characterized in that] wherein the support is composed of a material which is selected from the group consisting of ceramic, non-conducting cermet, plastic and[/or] composite material.—

--4. (amended) [Optoelectronic] The optoelectronic component group according to Claim [1] 14, [characterized in that] wherein at least one further component (7) is fixed on [the support] said exterior mounting surface.—

--5. (amended) [Optoelectronic] The optoelectronic component group according to Claim [3] 4, [characterized in that] wherein the further component is [an electronic circuit, in particular] an integrated circuit [or complete drive circuit, or an LED].--

--6. (amended) [Optoelectronic] The optoelectronic component group according to Claim 1, [characterized in that] wherein the component group is a component part of a surface lighting luminaire or lamp.--

--7. (amended) [Optoelectronic] The optoelectronic component group according to Claim 1, [characterized in that] wherein a plurality of the the LEDs (2) are arranged regularly on the support.-

--8. (amended) [Optoelectronic] The optoelectronic component group according to Claim 7, [characterized in that] wherein the LEDs (2) form [a section or] an array, with a prescribed distance (a and b) in the rows and columns, respectively.-

--9. (amended) [Optoelectronic] The optoelectronic component group according to Claim 6, [characterized in that] wherein the distance between the at least two adjacent LEDs is [at most 5mm, preferably] less than 2 mm.-

--10. (amended) [Optoelectronic] The optoelectronic component group according to Claim 1, [characterized in that] wherein the support is mounted on a further heat-dissipating [material, in particular a], separate thermal plate [or body parts of a vehicle].—

--11. (amended) [Optoelectronic] The optoelectronic component group according to Claim 2, [characterized in that] further[, in particular] comprising electronic component parts [are] integrated on [the support] said exterior mounting surface.—

--12. (amended) [Optoelectronic] The optoelectronic component group according to Claim 6, [characterized in that the] wherein a structural height of the group is less than 10 mm.

--13. (amended) [Optoelectronic] An optoelectronic component group which is mounted on an exterior mounting surface of a support (3) and which comprises at least two adjacent LEDs (2), which are spaced apart from one another, and also associated connecting lines (4), [characterized in that] wherein the support (3) [is composed of a material which] dissipates heat well

enough to realize a distance between adjacent LEDs of [at most 5 mm, preferably] less than 2 mm, without limiting the specified forward current of the LEDs and without further aids.—

The ABSTRACT OF THE DISCLOSURE was amended as follows:

--An optoelectronic component group has at least two LEDs (2) which are mounted on a support (3). The support is composed of a material having a thermal conductivity of better than [1] 1.5 W/Kxm, for example ceramic or composite material.—